

2827
#



FORM PTO-1083

Case Docket No. TM&K0006

Date: April 24, 2003

In re Application of: Shinji TAKEDA et al.

Serial No. 09/785,194

Filed: February 20, 2001

For: SEMICONDUCTOR DEVICE AND PROCESS FOR FABRICATION THEREOF

ASSISTANT COMMISSIONER FOR PATENTS

Box: NO FEE AMENDMENT
Washington, D. C. 20231

Sir:

Transmitted herewith is an Amendment in the above-identified application.

- [] Small entity status of this application under 37 CFR 1.9 and 1.27 has been established by a verified statement previously submitted.
- [] A verified statement to establish small entity status under 37 CFR 1.9 and 1.27 is hereby claimed.
- [XXX] No additional fee is required.

The fee has been calculated as shown below:

| The fee has been calculated as shown below: | | | | | | | | | | OTHER SMALL | THAN A ENTITY |
|---|--|---|----|---|--|------------------------------|--|----------------------|---------------|----------------|------------------|
| (COL. 1) CLAIMS REMAINING AFTER | | | | (COL. 2) HIGHEST NO. PREVIOUSLY PAID FOR | | (COL. 3) PRESENT EXTRA | | SMALL ENTITY RATE | ADDIT. FEE | OR RATE | ADDIT. FEE |
| AMENDMENT | | | | | | | | | | | |
| TOTAL | | * | 41 | MINUS ** 41 | | = 0 | | X 9 = \$ | | X 18 = \$ | |
| INDEP. | | * | 1 | MINUS *** 3 | | = 0 | | X 42 = \$ | | X 84 = \$ | |
| [] FIRST PRESENTATION OF MULTIPLE DEP. CLAIM | | | | | | | | X140 = \$ | | X280 = \$ | |

TOTAL
ADDIT. FEE \$ -0- OR TOTAL \$

- * If the entry in Col. 1 is less than the entry in Col. 2, write "0" in Col. 3.
 - ** If the "Highest No. Previously Paid For" IN THIS SPACE is less than 20, write "20" in this space.
 - *** If the "Highest No. Previously Paid For" IN THIS SPACE is less than 3, write "3" in this space.
- The "Highest No. Previously Paid For" (Total or Independent) is the highest number found from the equivalent box in Col. 1 of a prior Amendment or the number of claims originally filed.

- [] Please charge my Deposit Account No. 501281 in the amount of \$. A duplicate copy of this sheet is attached.
- [] A check (No.) in the amount of \$ is attached.
- [XXX] The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 501281. A duplicate copy of this sheet is attached.

- [XX] Any filing fees under 37 CFR 1.16 for the presentation of extra claims.
- [XX] Any patent application processing fees under 37 CFR 1.17.

Joerg-Uwe Szimpl
Reg. No. 31,799

PLEASE DIRECT ALL CORRESPONDENCE TO:

GRIFFIN & SZIPL, PC
Suite PH-1, 2300 9th Street, South
Arlington, VA 22204

Telephone: (703) 979-5700
Facsimile: (703) 979-7429
Customer No.: 24203

RECEIVED
APR 30 2003
TECHNOLOGY CENTER 2800



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Shinji TAKEDA et al.

Serial No. 09/785,194

Filed: February 20, 2001

For: SEMICONDUCTOR DEVICE AND
PROCESS FOR FABRICATION
THEREOF

)
) Atty. Docket No.: TM&K0006

)
) Group Art Unit: 2827

)
) Examiner: GRAYBILL, D.

)
) Date: April 24, 2003

AMENDMENT (C)

Box: Fee Amendment

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the official Office Action dated December 24, 2002, please amend the
above captioned application as follows.

IN THE CLAIMS

Kindly amend claim 31 as follows:

31. (Amended) A process according to claim 30, wherein said step of bonding
comprises bonding with an organic die-bonding film further having a void volume of 10% or less
in terms of voids present in the material of the film, and at an interface between said film and
said support at a stage where the semiconductor has been bonded to said support by said film.

RECEIVED
APR 30 2003
TECHNOLOGY CENTER 2800